

### **FEATURE**

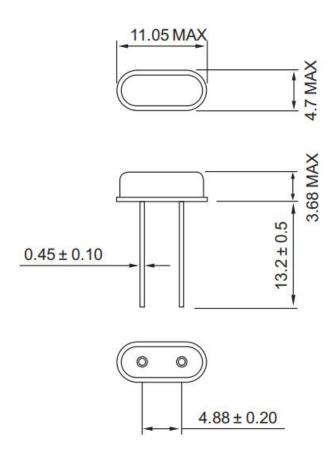
- Resistance welded type crystal units
- A great number of standard frequencies
- Higher frequency avail able and lower equivalent series resistance
- Lower cost and highly mass production capability
- RoHS Compliant / Pb Free

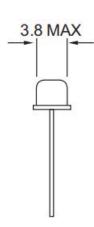
## 1. ELECTRICAL SPECIFICATIONS

| Hold Style   | HC-49/S                      |
|--|------------------------------|
| Nominal Frequency  | 9.216MHz                     |
| Mode   | Fundamental / AT             |
| Frequency Tolerance (at 25°C)                                  | ±30ppm                       |
| Frequency Stability Over Operating Temperature Characteristics | ±30ppm                       |
| Operating Temperature Range                                    | -20℃ ~ +70℃                  |
| Storage Temperature Range                                      | -40℃ ~ +85℃                  |
| Shunt Capacitance (C <sub>0</sub> )                            | 7.0pF Max                    |
| Driver Level (Typical)   | 100μW                        |
| Load Capacitance(C <sub>L</sub> )                              | 20pF                         |
| ESR  | 50Ω Max                      |
| Insulation Resistance  | More than 500Mohms at DC100V |
| Aging @25°C 1 <sup>st</sup> year (Max)                         | ±3ppm/year                   |

# SRPASSIVES

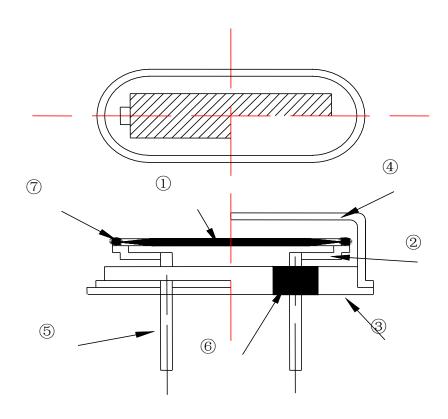
# 2. DIMENSIONS (Unit: mm)







## 3. STRUCTURE ILLUSTRATION



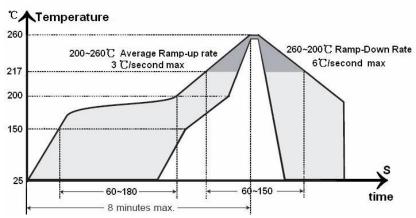
| NO | COMPONENT     | MATERIALS     | ОТУ | SURFACE                    |
|----|---------------|---------------|-----|----------------------------|
| 1  | CRYSTAL BLANK | SiO2          | 1   | POLISH/ETCHED              |
| 2  | SUPPORTER     | COPPER        | 2   |                            |
| 3  | BASE          | Fe-NI         | 1   | NI PLATED                  |
| 4  | CAN           | NICKEL-COPPER | 1   |                            |
| 5  | LEAD          | KOVAR         | 2   | NI PLATED+SOLDER<br>DIPPED |
| 6  | GLASS         | KOVER-GLASS   | 2   |                            |
| 7  | ADHESIVE GENT | Ag-URETHANE   | 2   |                            |



### 4. RELIABILITY SPECIFICATIONS

| ltem             | Item Conditions  |                                    |  |
|------------------|--|------------------------------------|--|
| Low Temp.        | Put the crystal into the -40 °C ±2 °C constant temperature box for                               | △F≦±5 PPM                          |  |
| Storage          | 500±2 H , Measurement taken after 2 hour.  | △RR≦±15% or                        |  |
|                  |  | 5 ohms                             |  |
| High Temp.       | Put the crystal into the $+100^{\circ}\text{C}\pm2^{\circ}\text{C}$ constant temperature box for | ∆F≦±5 PPM                          |  |
| Storage          | 500±2 H, Measurement taken after 2 hour.   | △RR ≦ ±15% or                      |  |
|                  | JOOTZ II, Weasurement taken after 2 nour.  | 5 ohms                             |  |
| High Temp &      | Put the crystal into the constant temperature & humid with the                                   | ∆F≦±5 PPM                          |  |
| Humidity         | temperatures 85 $^{\circ}$ C ±3 $^{\circ}$ C and the humidity 98% for 500±2 H.                   | △RR≦±15% or                        |  |
|                  | Measurement taken after 2 hour.  | 5 ohms                             |  |
| Thermal Shock    | Put the crystal into the constant temperature-55 $^{\circ}$ C ±2 $^{\circ}$ C for                | ΔF≦±5 PPM                          |  |
|                  | 30±1M, then change the temperature to +85 $^{\circ}$ C ±2 $^{\circ}$ C for 30±1M,                | △RR≦±15% or                        |  |
|                  | the total is 100times. Measurement taken after 2 hour.   | 5 ohms                             |  |
| Resistance To    | Passed through the re-flow oven under the following condition.                                   | ΔF≦±5 PPM                          |  |
| Soldering Heat   | Preheat to 150°C±5°C for 60 to 120 sec ,and peak 265°C±5°C for                                   | △RR≦±15% or                        |  |
| S                | 10s±3sec. Measurement taken after DUT being left at room temperature for at 24±2 hours           | 5 ohms                             |  |
| Drop Test        | The crystal fall off the cement floor with the height 75cm±5cm for                               | △F≦±5 PPM                          |  |
|                  | 3 time . Measurement taken after 2 hour.   | △RR≦±15% or                        |  |
|                  |  | 5 ohms                             |  |
| Vibration Test   | Apply 0.75mm vibration at sweep frequency 10 ~ 500 Hz, for 2h.                                   | ΔF≦±5 PPM                          |  |
|                  | 10 cycles in each direction of 3 axis. Measurement taken after 2                                 | △RR ≦ ±15% or                      |  |
|                  | hour.  | 5 ohms                             |  |
| Tensile strength | Apply a 1.5Kg tensile load to each terminal and sustain it for                                   | No visible damage,                 |  |
| of terminal      | 30±5 seconds.  | Leak OK                            |  |
| Bending strength | Apply a 0.5 Kg load to one of the terminals, and after tilting the                               | No visible damage,                 |  |
| of terminal      | main unit for 90°, restore to its original attitude. Then, tilt it in an                         | Leak OK                            |  |
|                  | opposite direction for 90°, and restore to its original attitude.                                |                                    |  |
| Fine Leak        | Take measurements with a helium leakage detector, or   | 1×10-2μPa . m3 /s                  |  |
|                  | measure insulation resistance under pressure.  | Max or IR≥500MΩ                    |  |
| Solder ability   | In 245 $\pm$ 5 $^{\circ}$ C solder bath for 2 $\pm$ 0.5 seconds. 8-12X magnifier.                | Terminals shall be                 |  |
|                  |  | covered more then 95% with solder. |  |





Peak temperature. 260 🍪 💠 (10sec. max.)

## 5. SUBSTANCES IN PRODUCT

| Drawing | component          | Homogeneous                             | nogeneous Substance Name CAS No. |            | Substance  | Content    |
|---------|--------------------|---|----------------------------------|------------|------------|------------|
| number  | description        | n Material Name. Substance Name CAS No. |                                  | CAS NO.    | Mass. (mg) | Rate(%)per |
|         | BASE               | Fe and its compounds                    | Fe                               | 7439-89-6  | 290.9292   | 99.76%     |
|         |                    |   | С                                | 7440-44-0  | 0.1458     | 0.05%      |
|         |                    |   | Mn                               | 7439-96-5  | 0.4958     | 0.17%      |
|         |                    |   | Р                                | 7723-14-0  | 0.035      | 0.01%      |
|         |                    |   | Si                               | 7440-21-3  | 0.0292     | 0.01%      |
|         | WIRE               | Kovar ring                              | Fe                               | 7439-89-6  | 12.9626    | 37.38%     |
|         |                    |   | Cobal                            | 7440-48-4  | 5.5091     | 15.89%     |
|         |                    |   | Nickel                           | 7440-02-0  | 4.5369     | 13.08%     |
|         |                    |   | Copper                           | 7440-50-8  | 10.3701    | 29.91%     |
|         |                    |   | Sn                               | 7440-31-5  | 0.6481     | 1.87%      |
|         |                    |   | Ag                               | 7440-22-4  | 0.6481     | 1.87%      |
|         | GLASS              |   | SiO2                             | 15468-32-3 | 27.083     | 70.00%     |
|         |                    |   | Al2O3                            | 1344-28-1  | 3.4821     | 9.00%      |
| HC-49/S |                    | GLASS                                   | B2O3                             | 1303-86-2  | 3.0952     | 8.00%      |
|         |                    |   | Li2O                             | 12057-24-8 | 0.4643     | 1.20%      |
|         |                    |   | Na2O                             | 1313-59-3  | 3.869      | 10.00%     |
|         |                    |   | K2O                              | 12136-45-7 | 0.5804     | 1.50%      |
|         | CAN                | Kovar                                   | Copper                           | 7440-50-8  | 97.8194    | 64.26%     |
|         |                    |   | Zn                               | 7440-66-6  | 28.3137    | 18.60%     |
|         |                    |   | Nickel                           | 7440-02-0  | 25.9543    | 17.05%     |
|         |                    |   | Fe                               | 7439-89-6  | 0.137      | 0.09%      |
|         | Crystal Blank      | Quartz                                  | SiO2                             | 14464-46-1 | 4.3658     | 100.00%    |
|         | Electrode          | Ag                                      | Ag                               | 7440-22-4  | 0.3122     | 100.00%    |
|         | Sliver<br>adhesive | Sliver                                  | Ag                               | 7440-22-4  | 3          | 75.00%     |
|         |                    | adhesive                                | Xylene                           | 1330-20-7  | 0.4        | 10.00%     |
|         |                    |   | C6H12O3                          | 111-15-9   | 0.152      | 3.80%      |
|         |                    |   | Isophorone                       | 78-59-1    | 0.448      | 11.20%     |